



# Product Information Sheet

## ***New & Improved DYNAPURGE® K “Dual Power” cleaning for a broad range of low-temp resins***

**DYNAPURGE K** is a low-temperature, non-abrasive, non-chemical engineered thermoplastic purging compound, formulated to flow naturally through the machine. Two unique ingredients provide for a “dual power” cleaning experience. A non-melting but softening thermoplastic scrubs while a proprietary additive expands, removing any contamination without leaving behind a residue.

<b>Applications:</b>	<b>Injection</b> - cold and hot runners <b>Extrusion</b> - profile, sheet, cast film & compounding
<b>Temperature Range:</b>	290° F - 550° F (143° C - 287° C)
<b>Types of Resins:</b>	PP, TPE, TPO, TPR, TPU & other low temperature resins
<b>Minimum Clearance:</b>	.025 inch or .65 mm
<b>Amount of Purge:</b>	1 to 2 times barrel capacity(actual amount needed depends on machine conditions)

### **FEATURES & BENEFITS:**

- Developed for color changes, resin changes, preventative machine maintenance, and before manual cleaning
- Excellent for purging through equipment with a minimum clearance of .025 inch (.65 mm) or greater
- Effective through a wide range of temperatures – 290°F to 550° F (143°C to 287°C)
- Easy to use – no process adjustment necessary – use at the resident resin processing temperature and RPM speed
- Non-abrasive, non-melting but softening thermoplastic, which thoroughly loosens carbonized and degraded resin, allowing it to be flushed out of the system
- Safe, non-hazardous, with no chemicals – ingredients are FDA compliant
- Heat stable – recommended during shutdown and start-up
- Low “cost-per-purge” – only a small quantity is needed to be effective
- No mixing required – simply use “as is”
- Unlimited shelf life

Dyna-Purge has been the top performing purging compound for almost 30 years! Our product line offers superior cleaning and economic value over in-house methods and other commercial purges. We invite you to sample Dyna-Purge at no charge, so you can prove it to yourself.

***Please refer to “Suggested Purging Procedures” for processing information and “Grade Selection Guide” regarding additional products.***